

IN THE SPECIFICATION

At page 3, before the heading "DETAILED DESCRIPTION OF THE INVENTION" add:

Fig. 16 is the structure of Fig. 14 with the space between element 153 and 11 filled with compliant medium 155.

At page 4, amend the second paragraph as follows:

FIG. 2 shows a cross section of an electronic circuit component (11) and several angled flying leads (10) attached to the first surface (12) of the component (11) according to the present invention. The angled flying leads (10) can be attached to a variety of different electronic circuit components (11). The angled flying leads (10) are bonded to metallized circuit pads (13) on the first surface (12) of the electronic circuit component (11). The electronic circuit component (11) must provide a rigid base for the thermosonic wire bonding process to be successful. FIGS. 1, 2, and 3 of the angled flying lead wire bonding process are essentially the same as a standard thermosonic wire bonding process. An electrical discharge (22) from an electronic flame off (EFO) unit (21) at surface 20 is used to melt the end of the bond wire (16) extending through the tip of a ceramic capillary tool (15). The electrical discharge (22) is controlled to provide a consistent sized ball (14) on the end of the bond wire (16).

At page 7 amend the third paragraph as follows:

FIG. 15 is a schematic diagram showing the structures according to the present invention in testing apparatus. The testing apparatus 208 has a means ~~[[207]]~~ 202 for disposing the probe tip ends 210 on a substrate 200 in contact with contact locations 212 on the device under test 204 which is disposed on support 206.